

DESIGNED & DIMENSIONED  
IN MILLIMETERS [INCHES]

TABLE 1

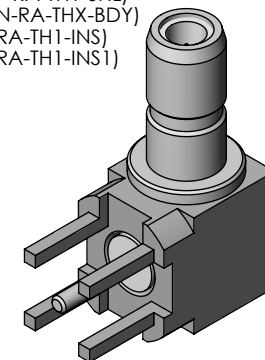
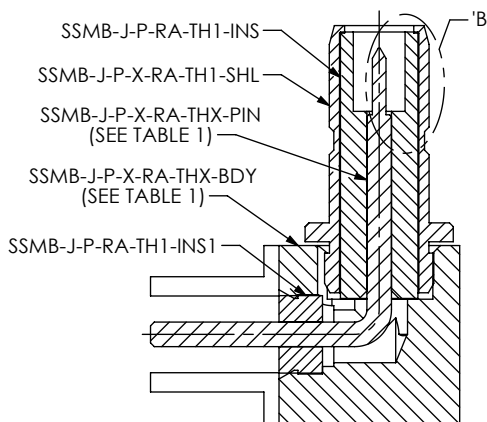
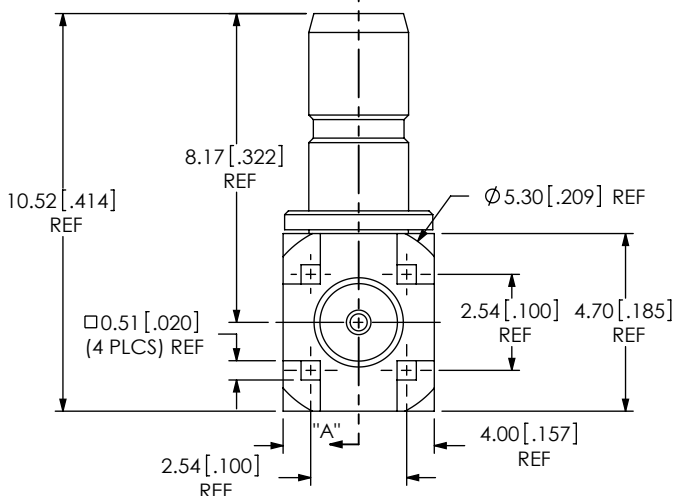
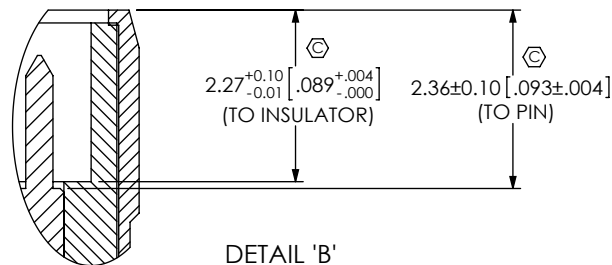
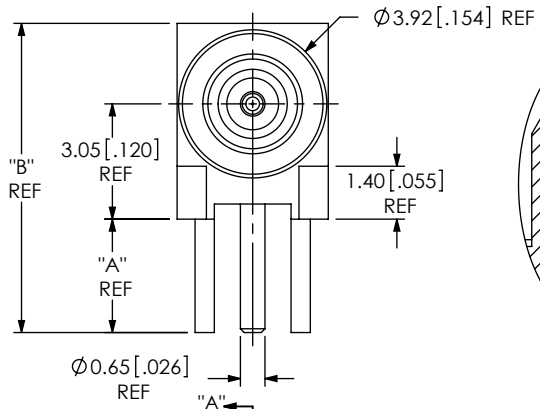
LEAD STYLE	"A"	"B"	SSMB-J-P-X-RA-THX-PIN	SSMB-J-P-X-RA-THX-BDY
-1	3.00 [0.118]	8.18 [0.322]	SSMB-J-P-X-RA-TH1-PIN	SSMB-J-P-X-RA-TH1-BDY
-2	2.20 [0.087]	7.38 [0.291]	SSMB-J-P-X-RA-TH2-PIN	SSMB-J-P-X-RA-TH2-BDY
-3	1.60 [0.063]	6.78 [0.267]	SSMB-J-P-X-RA-TH3-PIN	SSMB-J-P-X-RA-TH3-BDY

SSMB-J-P-XX-RA-THX

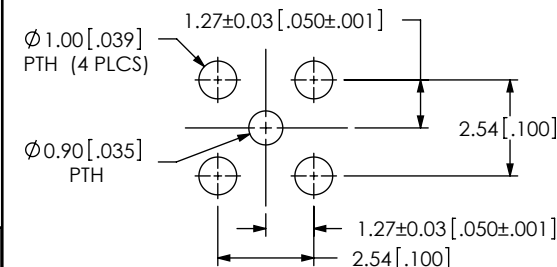
GENDER  
-J: JACK  
  
TYPE  
-P: PCB

LEAD STYLE  
-1: .093" BOARD  
-2: .062" BOARD  
-3: .039" BOARD  
(SEE TABLE 1)  
  
TERMINATION  
-TH: THROUGH HOLE  
  
ORIENTATION  
-RA: RIGHT ANGLE

PLATING SPECIFICATION  
-HG: HEAVY GOLD/GOLD (SEE NOTES 4 & 5)  
(SSMB-J-P-H-RA-THX-PIN)  
(SSMB-J-P-G-RA-TH1-SHL)  
(SSMB-J-P-N-RA-THX-BDY)  
(SSMB-J-P-RA-TH1-INS)  
(SSMB-J-P-RA-TH1-INS1)  
  
-GF: GOLD/NICKEL (SEE NOTES 4 & 5)  
(SSMB-J-P-G-RA-THX-PIN)  
(SSMB-J-P-F-RA-TH1-SHL)  
(SSMB-J-P-N-RA-THX-BDY)  
(SSMB-J-P-RA-TH1-INS)  
(SSMB-J-P-RA-TH1-INS1)



RECOMMENDED PCB LAYOUT



NOTES: **A**

- ⊙ REPRESENTS A CRITICAL DIMENSION.
- PRODUCT TO BE PACKAGED PER PACKING STANDARD CO-HD-WI-3040-M.  
TRAY: TY-SMA001-1  
COVER: TY-SMA001-2  
200 PARTS PER TRAY (2 PARTS PER POCKET)
- ROHS COMPLIANT.
- COMPONENT PLATING DESIGNATIONS:  
-H: .000030" MIN. GOLD OVER .000050" MIN. NICKEL.  
-G: .000010" MIN. GOLD OVER .000050" MIN. NICKEL.  
-F: .000003" MIN. GOLD OVER .000050" MIN. NICKEL.  
-N: .000100" MIN. NICKEL.
- ASSEMBLY PLATING DESIGNATIONS:  
-HG: (CENTER CONTACT)-H  
(OUTER CONTACT)-G  
(REMAINING METAL PARTS)-N  
-GF: (CENTER CONTACT)-G  
(OUTER CONTACT)-F  
(REMAINING METAL PARTS)-N

**THIS PRODUCT MANUFACTURED WITH LEAD-FREE PROCESSING**

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES]. TOLERANCES ARE:  
DECIMALS ANGLES  
.X: ±0.3 [0.1] 5°  
.XX: ±0.13 [0.005]  
.XXX: ±0.051 [0.0020]

**PROPRIETARY NOTE**  
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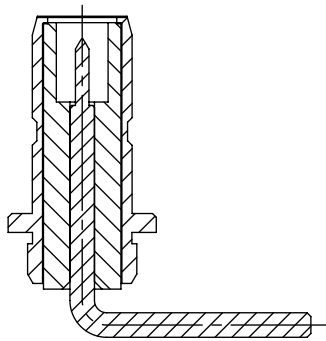


520 PARK EAST BLVD, NEW ALBANY, IN 47150  
PHONE: 812-944-6733 FAX: 812-948-5047  
e-Mail: info@SAMTEC.com code: 55322

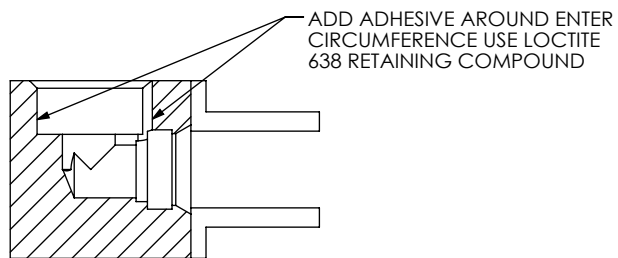
**MATERIAL:** DO NOT SCALE DRAWING SHEET SCALE: 5:1  
BODY, SHELL: BRASS  
PIN: BRASS  
DIELECTRIC: PTFE

DESCRIPTION:  
SSMB RIGHT ANGLE, JACK, 50 OHM  
DWG. NO.  
**SSMB-J-P-XX-RA-THX**  
BY: DUKES Z 9/20/2010 SHEET 1 OF 2

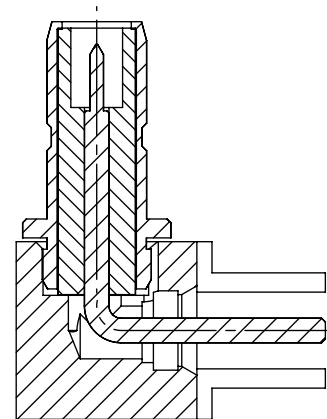
REVISION A



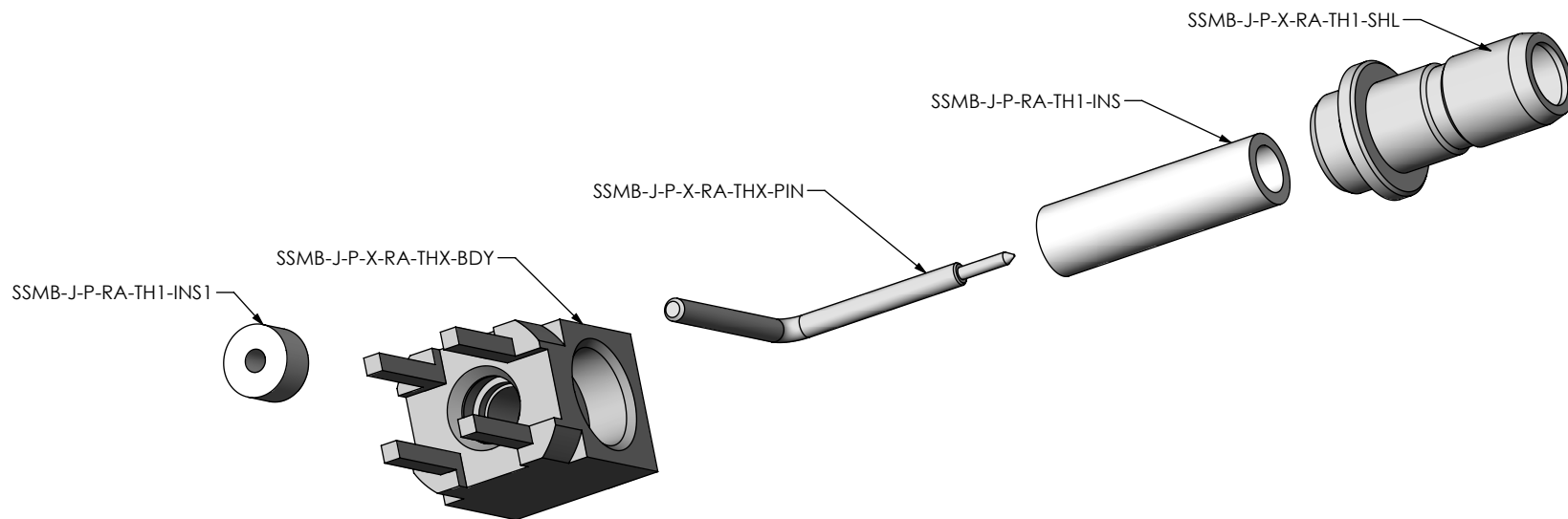
IN-PROCESS 1  
ADD INSULATOR AND SHELL TO PIN



ADD ADHESIVE AROUND CENTER CIRCUMFERENCE USE LOCTITE 638 RETAINING COMPOUND



IN-PROCESS 2  
ADD ADHESIVE/PRESS SHELL



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DO NOT SCALE DRAWING

SHEET SCALE: 5:1

**samtec**

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SSMB RIGHT ANGLE, JACK, 50 OHM

DWG. NO.  
SSMB-J-P-XX-RA-THX

BY: DUKES Z 9/20/2010 SHEET 2 OF 2